



Semi-Shielded Inductor 1.0µH



APPLICATIONS

- · Battery-powered devices
- High-efficiency SMPS
- Embedded computing
- Input filters

FEATURES

- Size 4.9mmx4.9mmx4mm
- Semi-Shielded Construction
- Low DCR
- Low Stray Field
- Max Operating Temp +125°C
- RoHS/REACH-Compliant, Halogen-Free

ELECTRICAL CHARACTERISTICS					
Parameter			Value	Unit	
Inductance (1)	L	±20%	1.0	μH	
Resistance	R _{DC}	typ	9.4	mΩ	
Resistance MAX	RDC MAX	max	11	$\boldsymbol{m\Omega}$	
Rated Current (2)	I _R	typ	7.6	Α	
Saturation Current 25°C (3)	ISAT 25°C	typ	10.5	Α	
Saturation Current 100°C (4)	ISAT 100°C	typ	9	Α	
Resonance Frequency	fr	typ	105	MHz	

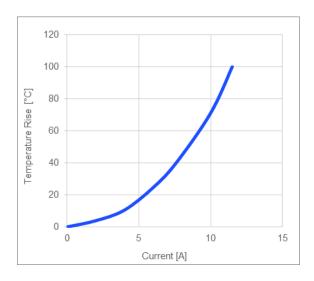
GENERAL SPECIFICATIONS		
(1) Inductance	Measured at 100kHz, 100mA	
(2) Rated Current	Rated current will cause the coil temperature rise ΔT of 40K I_R measured with the inductor soldered in a single-layer PCB. Copper layer thickness 35 μ m Cu / PCB size 30x50mm. Temperature behavior dependent on circuit design, PCB layout, proximity to other components, and trace dimensions and thickness.	
(3) Saturation Current 25°C	Saturation current will cause L to drop from 30% at 25°C ambient temperature	
(4) Saturation Current 100°C	Saturation current will cause L to drop from 30% at 100°C ambient temperature	
Temperature Test Condition	Electrical specifications measured at 25°C, 35% RH if not given differently	
Operating Condition	Operating temperature: -40°C to +125°C (including temp rise)	
	Should not exceed +125°C under worst-case operation conditions	
Storage Condition	Tape and Reel packaging: -10°C to +40°C Humidity: <50% RH	

All MPS parts are lead-free, halogen-free, and adhere to the RoHS directive. For MPS green status, please visit the MPS website under Quality Assurance. "MPS", the MPS logo, and "Simple, Easy Solutions" are registered trademarks of Monolithic Power Systems, Inc. or its subsidiaries.

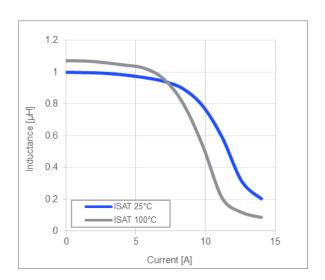


TYPICAL PERFORMANCE CURVES

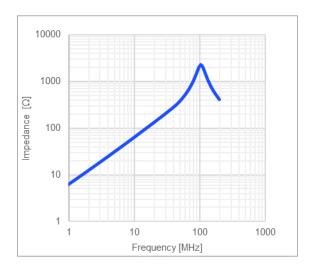
Temperature Rise vs. Current



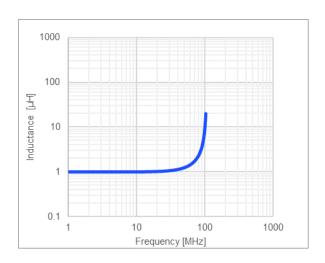
Inductance vs. Current



Impedance vs. Frequency

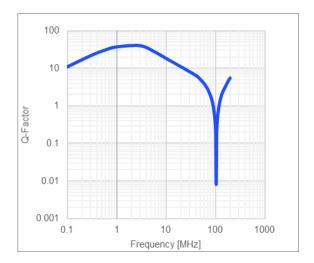


Inductance vs. Frequency

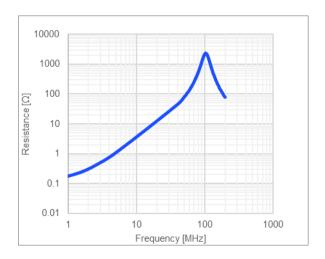




Quality Factor vs. Frequency

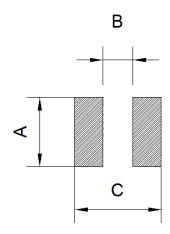


AC Resistance vs. Frequency





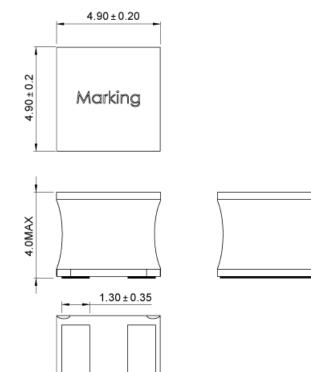
LAND PATTERN			
Dimensions			
Α	4.0 ref.		
В	2.10 ref.		
С	5.10 ref.		
	(unit in mm)		



PRODUCT PACKAGE AND DIMENSIONS

Dimensions

(unit in mm)



1.90 ref.

TOP MARKING Marking

Inductance Code 1R0



ORDERING INFORMATION					
Part Number	L (1)	RDC	I _R (2)	I _{SAT 25°C} (3)	ISAT 100°C (4)
	typ (µH)	typ (mΩ)	typ (A)	typ (A)	typ (A)
MPL-SE5040-R47	0.47	7.3	8.0	16	13.5
MPL-SE5040-1R0	1.0	9.4	7.6	10.5	9
MPL-SE5040-1R5	1.5	14	6.2	9.3	8.4
MPL-SE5040-2R2	2.2	16	5.4	7.9	7.3
MPL-SE5040-3R3	3.3	22	5.2	6.4	5.2
MPL-SE5040-4R7	4.7	33	4.3	5	4.6
MPL-SE5040-6R8	6.8	45	3.5	4.6	4
MPL-SE5040-100	10	56	3.2	3.6	3
MPL-SE5040-150	15	83	2.5	2.9	2.6
MPL-SE5040-220	22	124	2.1	2.4	2.15

GENERAL SPECIFICATIONS	
(1) Inductance	Measured at 100kHz, 100mA
(2) Rated Current	Rated current will cause the coil temperature rise ΔT of 40K I_R measured with the inductor soldered in a single-layer PCB. Copper layer thickness 35 μ m Cu / PCB size 30x50mm. Temperature behavior dependent on circuit design, PCB layout, proximity to other components, and trace dimensions and thickness.
(3) Saturation Current 25°C	Saturation current will cause L to drop from 30% at 25°C ambient temperature
(4) Saturation Current 100°C	Saturation current will cause L to drop from 30% at 100°C ambient temperature
Temperature Test Condition	Electrical specifications measured at 25°C, 35% RH if not given differently
Operating Condition	Operating temperature: -40°C to +125°C (including temp rise)
	Should not exceed +125°C under worst-case operation conditions
Storage Condition	Tape and Reel packaging: -10°C to +40°C Humidity: <50% RH

NOTICE: The information in this document is subject to change without notice. Please contact MPS for current specifications. Users should warrant and guarantee that third-party Intellectual Property rights are not infringed upon when integrating MPS products into any application. MPS will not assume any legal responsibility for any said applications.